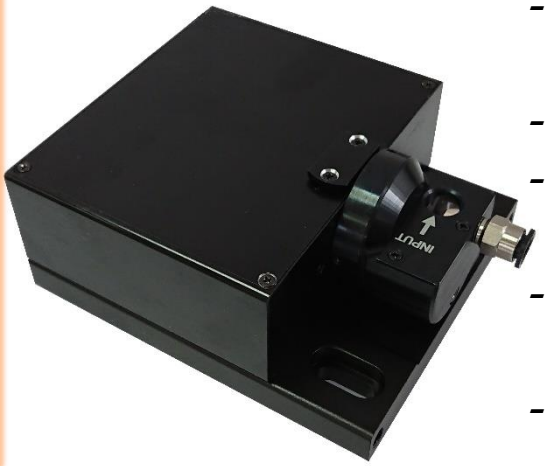
LAM Beam Analyzer



- High power beam measurements at the working tabletop.
- Built-in air-cooled sampler
- Industry's leading knife-edge system
- Unique tomographic image reconstruction
- Beam measurements down to 35 microns and up to 8 mm
- Accurately measures profile, position and power

Specifications

Laser Type	CW
Beam width resolution	For beams > 100 µm in size: 1 µm. For beams <100 µm in size: 0.1 µm
Beam Size	35 µm - ⌀8 mm
Spectral Response	Si: 350 - 1100 nm. Contact factory for other wavelengths
Resolution (H x V pixels)	Adaptive according to beam size
Sensor Active Area (mm)	9 x 9
Number of Blades	7 blades with image tomographic reconstruction
Gain Control	Automatic
Frame Rate	5 fps
Working Distance	49 mm (contact factory)
Maximum BPP	Max. input angle – 25 deg.
Maximum power density	1,000,000 W/cm² (contact factory)
Power measuring	With user's pre-calibration at a selected point

Power range @900/1070 nm	Up to 4 kW (with filters & pressurized air-cooling, some restrictions may apply)
Output power from back side of beam sampler	With beam dump – no significant output power
Cooling conditions	Filtered pressurized air of 6-8 Bar
Sensor type	Silicone (Si) - Knife-edge technology
Beam width accuracy	±1.5%
Power accuracy	±5%
Position resolution	1 µm
Pixel Size	Adaptive according to beam size
Pixel Bit Depth	12 bits
Background Subtraction	Automatic
Power Requirements	~2.5 Watt (Via USB 2.0 interface)
Dimensions (L x W x H) in mm	147 x 105 x 48
Weight (typical)	Sensor head with cable ~ 1500 gr.
Min. Hardware Requirements	CPU i3 1.6 GHz, 4 GB RAM
Interface	USB 2.0, Windows 7/8/10 (32 & 64 bit)
Operating Temperature	0° – 35° C

Ordering Information

LAM-BA: 7-blades, Si detector with high power attenuator and mounting adapter.

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